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Date : 2020/04/24

APPROVAL SHEET

Product Name : Medium Voltage Multilayer Ceramic Chip Capacitors

Part No. : FM43X474K501EGG

Description : Size 1812, X7R, 470nF, ±10%, 500V

PREPARED BY	APPROVED BY

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SPECIFICATION

FOR

Product Name : Medium Voltage Multilayer Ceramic Chip Capacitors

Part No. : FM43X474K501EGG

Description : Size 1812, X7R, 470nF, ±10%, 500V

SPEC. No. : FM-083-033-01

DATE : 2020/04/24

DRAWN BY	CHECEKED BY	APPROVED BY
<i>Jane Hsiao</i>	<i>Yvens Chou</i>	<i>Joseph Ling</i>

1. INTRODUCTION

FM Series green type capacitors are manufactured by using green materials without lead and cadmium. These capacitors feature series connection of multi-layer capacitor units in a MLCC to realize high voltage performance. Reliable performances are built-in through exact formulation of dielectric powders, preparation of conductive paste, advanced automatic manufacturing, and strict quality control to assure excellent control in dielectric thickness, electrode integrity, and electrode-to-termination continuity.

2. FEATURES

- Medium voltage in a given case size.
- High reliability and stability.
- RoHS compliant.

3. APPLICATIONS

- DC to DC converter.
- High voltage coupling/DC blocking.
- Back-lighting inverters.
- Snubbers in high frequency power converters.

4. HOW TO ORDER

<u>FM</u>	<u>43</u>	<u>X</u>	<u>474</u>	<u>K</u>	<u>501</u>	<u>E</u>	<u>G</u>	<u>G</u>
PDC Family	Size	Dielectric	Capacitance	Tolerance	Rated Voltage	Packaging	Thickness	Control Code
Table 1	Table 2	Table 3	Table 4	Table 5	Table 6	Table 7	Table 8	Table 9

Table 1		PDC Family	
Code	Description		
FM	100V≤Rated Voltage≤630V series		

Table 6		Rated Voltage			
Code	Description	Code	Description	Code	Description
101	100Vdc	251	250Vdc	501	500Vdc
201	200Vdc	401	400Vdc	631	630Vdc

Table 2		Size			
Code	Description	Code	Description	Code	Description
15	0402 (1005)	32	1210 (3225)	52	2211 (5728)
18	0603 (1608)	42	1808 (4520)	55	2220 (5750)
21	0805 (2012)	43	1812 (4532)	56	2225 (5763)
31	1206 (3216)	46	1825 (4563)		

Table 7		Packaging Type	
Code	Description	Code	Description
B	Bulk	T	Tray package
E	Tape and 7" Reel, Embossed Tape	P	Tape and 7" Reel, Paper Tape
K	Tape and 10" Reel, Embossed Tape	D	Tape and 10" Reel, Paper Tape
L	Tape and 13" Reel, Embossed Tape	G	Tape and 13" Reel, Paper Tape

Table 3		Dielectric Material Characteristics	
Code	Description	Code	Description
N	C0G	X	X7R
F	Y5V		

Table 8		Thickness Description			
Code	Description	Code	Description	Code	Description
A	0.60 ± 0.10 mm	I	1.25 ± 0.20 mm	Q	0.50 +0.02/-0.05 mm
B	0.8 + 0.15/-0.10 mm	J	1.15 ± 0.15 mm	R	3.10 ± 0.30 mm
C	1.25 ± 0.10 mm	K	0.50 ± 0.20 mm	S	0.80 ± 0.07 mm
D	1.40 ± 0.15 mm	L	0.30 ± 0.03 mm	T	0.85 ± 0.10 mm
E	1.60 ± 0.20 mm	M	0.95 ± 0.10 mm	U	0.50 ± 0.10 mm
F	2.00 ± 0.20 mm	N	0.50 ± 0.05 mm	V	0.20 ± 0.02 mm
G	2.50 ± 0.30 mm	O	3.50 ± 0.20 mm	X	0.80 ± 0.10 mm
H	2.80 ± 0.30 mm	P	1.60 +0.3/-0.10 mm	Z	0.25 ± 0.03 mm

Table 4		Capacitance Rule Code	
Code	Description	Code	Description
R47	0.47pF	102	102=10x10 ² =1000pF
0R5	0.5pF	104	104=10x10 ⁴ =100nF
100	100=10x10 ⁰ =10pF	106	106=10x10 ⁶ =10μF

Table 9		Special Control Code	
Code	Description		
G	RoHS Compliant		
Q	Surface Coating (Size 1206~2225)		

Table 5		Tolerance			
Code	Description	Code	Description	Code	Description
A	±0.05 pF	J	±5 %	X	+10%~+20%
B	±0.10 pF	K	±10 %		
C	±0.25 pF	L	0% ~ +10%		
D	±0.50 pF	M	±20 %		
F	±1 %	N	-5% ~ +10%		
G	±2 %	P	±0.02 pF		
H	±3 %	Q	±0.03 pF		
I	-10% ~ 0%	Z	-20% ~ +80%		

5. EXTERNAL DIMENSIONS

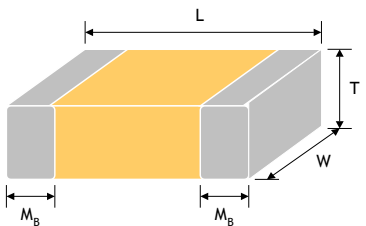
Size Inch (mm)	L (mm)	W (mm)	Code / T (mm)	M _B (mm)	
0402(1005)	1.00±0.10	0.50±0.10	See No.4 Reference Table 8	0.25 +0.05/-0.10	
0603(1608)	1.60±0.15	0.80±0.15		0.40±0.15	
0805(2012)	2.00±0.20	1.25±0.20		0.50±0.20	
1206(3216)	3.20±0.20 3.20 +0.30/-0.10 [#]	1.60±0.20 1.60 +0.30/-0.10 [#]		0.60±0.20	
1210(3225)	3.20±0.30	2.50±0.30		0.75±0.35	
1808(4520)	4.50±0.40	2.00±0.25		0.75±0.35	
1812(4532)	4.50±0.40	3.20±0.30		0.75±0.35	
1825(4563)	4.50±0.40	6.30±0.40		0.75±0.35	
2220(5750)	5.70±0.40	5.00±0.40		0.85±0.35	
2225(5763)	5.70±0.40	6.30±0.40		0.85±0.35	

Fig. 5.1 The outline of MLCC

[#]For 1206 size P thickness products.

6. GENERAL ELECTRICAL DATA

Dielectric	C0G	X7R	Y5V						
Size	0402, 0603, 0805, 1206, 1210, 1808, 1812, 1825, 2220, 2225	0402, 0603, 0805, 1206, 1210, 1808, 1812, 1825, 2220, 2225	0805, 1206, 1210, 1812						
Rated voltage (WVDC)	100V, 200V, 250V, 500V, 630V	100V, 200V, 250V, 450V, 500V, 630V	100V, 200V, 250V						
Capacitance range	0.5pF ~ 100nF	100pF ~ 820nF	10nF to 680nF						
Capacitance tolerance	Reference to Table5	Reference to Table5	Reference to Table5						
Tan δ	<table border="1"> <thead> <tr> <th>Cap. Rang</th> <th>Q Spec.</th> </tr> </thead> <tbody> <tr> <td>Cap.<30pF</td> <td>Q≥400+20C</td> </tr> <tr> <td>Cap.≥30pF</td> <td>Q≥1000</td> </tr> </tbody> </table>	Cap. Rang	Q Spec.	Cap.<30pF	Q≥400+20C	Cap.≥30pF	Q≥1000	≤2.5% ~ ≤10.0%	≤5.0%
Cap. Rang	Q Spec.								
Cap.<30pF	Q≥400+20C								
Cap.≥30pF	Q≥1000								
Capacitance & Tan δ Test condition	Measured at the condition of 30~70% related humidity For 25°C at ambient temperature Preconditioning for Class II MLCC : Perform a heat treatment at 150±10°C for 1 hour, then leave in ambient condition for 24±2 hours before measurement								
	<table border="1"> <thead> <tr> <th>Cap. Rang</th> <th>Test Condition</th> </tr> </thead> <tbody> <tr> <td>Cap.≤1000pF</td> <td>1.0±0.2Vrms, 1.0MHz±10%</td> </tr> <tr> <td>Cap.>1000pF</td> <td>1.0±0.2Vrms, 1.0KHz±10%</td> </tr> </tbody> </table>	Cap. Rang	Test Condition	Cap.≤1000pF	1.0±0.2Vrms, 1.0MHz±10%	Cap.>1000pF	1.0±0.2Vrms, 1.0KHz±10%	1.0±0.2Vrms, 1.0KHz±10%, at 25°C ambient temperature	1.0±0.2Vrms, 1.0KHz±10%, at 20°C ambient temperature
Cap. Rang	Test Condition								
Cap.≤1000pF	1.0±0.2Vrms, 1.0MHz±10%								
Cap.>1000pF	1.0±0.2Vrms, 1.0KHz±10%								
Insulation resistance at Ur	≥10GΩ or RxC≥500Ω-F, whichever is smaller	≥10GΩ or RxC≥100Ω-F, whichever is smaller							
Operating temperature	-55 to +125°C		-25 to +85°C						
Capacitance characteristic	±30ppm/°C	±15%	+30/-80%						
Termination	Cu/Ni/Sn or Au (lead-free termination)								

7. PACKAGE DIMENSION AND QUANTITY

Size	Thickness (mm)	Paper tape		Plastic tape	
		7" reel	13" reel	7" reel	13" reel
0201(0603)	0.30±0.03	15k	70k	-	-
	0.30±0.05	15k	-	-	-
	0.30±0.09	15k	-	-	-
0402(1005)	0.50±0.05	10k	50k	-	-
	0.50 +0.02/-0.05	10k	50k	-	-
0603(1608)	0.50±0.20	10k	-	-	-
	0.50±0.10	4k	-	-	-
	0.80±0.07	4k	15k	-	-
0805(2012)	0.80 +0.15/-0.10	4k	15k	-	-
	0.50±0.10	4k	15k	-	-
	0.60±0.10	4k	15k	-	-
1206(3216)	0.80±0.10	4k	15k	-	-
	0.85±0.10	4k	15k	-	-
	0.95±0.10	-	-	3k	10k
	1.15±0.15	-	-	3k	10k
	1.25±0.10	-	-	3k	10k
	1.60±0.20	-	-	2k	10k
1210(3225)	1.60 +0.30/-0.10	-	-	2k	9k
	0.85±0.10	-	-	3k	10k
	0.95±0.10	-	-	3k	10k
	1.25±0.10	-	-	3k	10k
	1.60±0.20	-	-	2k	-
	2.00±0.20	-	-	1k	6k
1808(4520)	2.50±0.30	-	-	1k	6k
	1.25±0.10	-	-	2k	10k
	1.60±0.20	-	-	2k	8k
1812(4532)	2.00±0.20	-	-	1k	6k
	2.00±0.20	-	-	1k	-
	2.50±0.30	-	-	0.5k	3k
	2.80±0.30	-	-	0.5k	-
1825(4563)	1.60±0.20	-	-	1k	-
	2.00±0.20	-	-	1k	-
	2.50±0.30	-	-	0.5k	-
	2.80±0.30	-	-	0.5k	-
2220(5750)	1.60±0.20	-	-	1k	-
	2.00±0.20	-	-	1k	-
	2.50±0.30	-	-	0.5k	-
	2.80±0.30	-	-	0.5k	-
2225(5763)	1.60±0.20	-	-	1k	-
	2.00±0.20	-	-	1k	-
	2.50±0.30	-	-	0.5k	-
	2.80±0.30	-	-	0.5k	-

Unit : pcs

7. PACKAGE DIMENSION AND QUANTITY

7.1. EMBOSSED TAPE DIMENSIONS

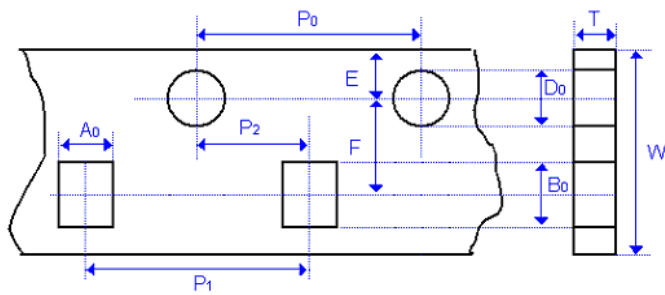


Fig. 7.1 The dimension of paper tape

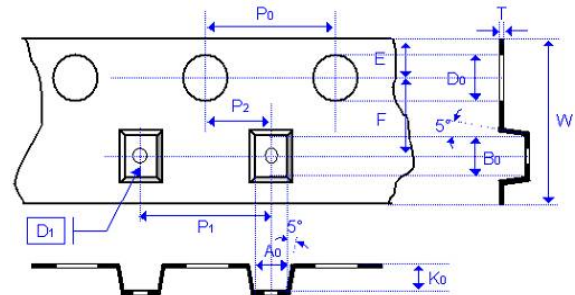


Fig. 7.2 The dimension of plastic tape

Size	0201	0402	0603		0805	
Chip Thickness	0.30±0.03	0.50±0.05 0.50±0.10	0.80±0.07	0.80 +0.15/-0.1	0.80±0.10	1.25±0.10 1.25±0.20
A ₀	0.39±0.07	0.70±0.20	1.00 +0.05/-0.10	1.02 +0.05/-0.10	1.50±0.10	<1.65
B ₀	0.69±0.07	1.20±0.20	1.80±0.10	1.80±0.10	2.30±0.10	<2.40
T	≤0.50	≤0.80	0.95±0.05	0.97±0.05	0.95±0.05	0.23±0.05
K ₀	-	-	-	-	-	<2.50
W	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10
P ₀	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10
10xP ₀	40.00±0.10	40.00±0.10	40.00±0.20	40.00±0.20	40.00±0.20	40.00±0.20
P ₁	2.00±0.05	2.00±0.05	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10
P ₂	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05
D ₀	1.55±0.05	1.55±0.05	1.55±0.05	1.55±0.05	1.55±0.05	1.50 +0.10/-0
D ₁	-	-	-	-	-	1.00±0.10
E	1.75±0.05	1.75±0.05	1.75±0.05	1.75±0.05	1.75±0.05	1.75±0.10
F	3.50±0.05	3.50±0.05	3.50±0.05	3.50±0.05	3.50±0.05	3.50±0.05
Unit :	mm	mm	mm	mm	mm	mm

Size	1206			1210		1812	
Chip Thickness	0.80±0.10	0.95±0.10 1.25±0.10	1.60±0.20 1.60±0.3/-0/1	0.95±0.10 1.25±0.10 1.60±0.20	2.50±0.30	1.25±0.10 1.60±0.20 2.00±0.20	2.50±0.30
A ₀	2.00±0.10	<2.00	<2.00	<3.05	<3.10	<3.90	<3.90
B ₀	3.50±0.10	<3.60	<3.70	<3.80	<4.00	<5.30	<5.30
T	0.95±0.05	0.23±0.05	0.23±0.05	0.23±0.05	0.23±0.05	0.25±0.05	0.25±0.05
K ₀	-	<2.50	<2.50	<2.50	<3.50	<2.50	<3.00
W	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10	12.00±0.20	12.00±0.20
P ₀	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10
10xP ₀	40.00±0.20	40.00±0.20	40.00±0.20	40.00±0.20	40.00±0.20	40.00±0.20	40.00±0.20
P ₁	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	8.00±0.10	8.00±0.10
P ₂	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05
D ₀	1.55±0.05	1.50 +0.10/-0	1.50 +0.10/-0	1.50 +0.10/-0	1.50 +0.10/-0	1.50 +0.10/-0	1.50 +0.10/-0
D ₁	-	1.00±0.10	1.00±0.10	1.00±0.10	1.00±0.10	1.50±0.10	1.50±0.10
E	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10
F	3.50±0.05	3.50±0.05	3.50±0.05	3.50±0.05	3.50±0.05	5.50±0.05	5.50±0.05
Unit :	mm	mm	mm	mm	mm	mm	mm

7. PACKAGE DIMENSION AND QUANTITY

Size	1825		2220		2225	
Chip Thickness	1.60±0.20 2.00±0.20	2.50±0.30	1.40±0.15 1.60±0.20 2.00±0.20	2.50±0.30	1.60±0.20 2.00±0.20	2.50±0.30
A ₀	<6.80	<6.80	<5.80	<5.80	<6.80	<6.80
B ₀	<5.30	<5.30	<6.50	<6.50	<6.50	<6.50
T	0.30±0.10	0.30±0.10	0.30±0.10	0.30±0.10	0.30±0.10	0.30±0.10
K ₀	<2.50	<3.10	<2.50	<3.10	<2.50	<3.10
W	12.00±0.20	12.00±0.20	12.00±0.20	12.00±0.20	12.00±0.20	12.00±0.20
P ₀	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10
10xP ₀	40.00±0.20	40.00±0.20	40.00±0.20	40.00±0.20	40.00±0.20	40.00±0.20
P ₁	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10
P ₂	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05
D ₀	1.50 +0.10/-0	1.50 +0.10/-0	1.50 +0.10/-0	1.50 +0.10/-0	1.50 +0.10/-0	1.50 +0.10/-0
D ₁	1.50±0.10	1.50±0.10	1.50±0.10	1.50±0.10	1.50±0.10	1.50±0.10
E	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10
F	5.50±0.05	5.50±0.05	5.50±0.05	5.50±0.05	5.50±0.05	5.50±0.05
Unit :	mm	mm	mm	mm	mm	mm

7.2. REEL DIMENSIONS

Size	0201, 0402, 0603, 0805, 1206, 1210		1808, 1812, 1825, 2220, 2225
Reel size	7"	13"	7"
C	13.0 +0.5/-0.2	13.0 +0.7/-0.3	13.0 +0.5/-0.2
W ₁	8.4 +1.5/-0	8.4 +2.0/-0	12.4 +2.0/-0
A	178.0 ±0.10	330.0 ±1.0	178.0 ±0.10
N	60.0 +1.0/-0	100 ±1.0	60.0 +1.0/-0

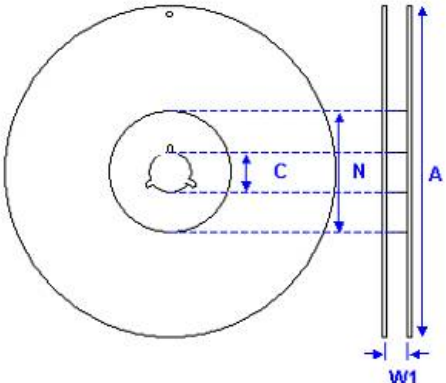


Fig. 7.3 The dimension of reel

8. APPLICATION NOTES

STORAGE

To prevent the damage of solderability of terminations, the following storage conditions are recommended :
 Indoors under 5 ~ 40°C and 20% ~ 70% RH.

No harmful gases containing sulfuric acid, ammonia, hydrogen sulfide or chlorine.

Packaging should not be opened until the capacitors are required for use. If opened, the pack should be re-sealed as soon as is practicable. Taped product should be stored out of direct sunlight, which might promote deterioration in tape or adhesion performance. The product is recommended to be used within 12 months after shipment and checked the solderability before use.

HANDLING

Chip capacitors are dense, hard, brittle, and abrasive materials. They are liable to suffer mechanical damage, in the form of cracks or chips. Chip Capacitors should be handled with care to avoid contamination or damage. To use vacuum or plastic tweezers to pick up or plastic tweezers is recommended for manual placement. Tape and reeled packages are suitable for automatic pick and placement machine.

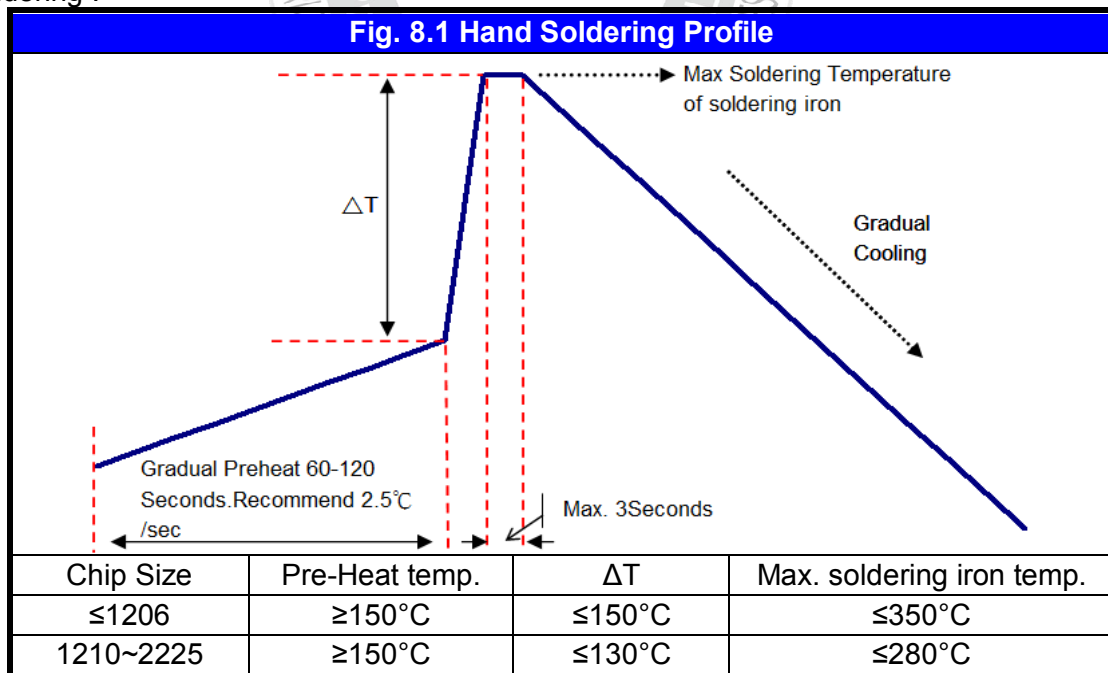
PREHEAT

In order to minimize the risk of thermal shock during soldering, a carefully controlled preheat is required. The rate of preheat should not exceed 3°C per second.

SOLDERING

Use middy activated rosin RA and RMA fluxes do not use activated flux. The amount of solder in each solder joint should be controlled to prevent the damage of chip capacitors caused by the stress between solder, chips, and substrate.

a.) Hand soldering :



* Soldering iron tip diameter ≤1.0 mm and wattage max. 20W.

* The Capacitors shall be pre-heated and that the temperature gradient between the devices and the tip of the soldering iron.

* The required amount of solder shall be melted on the soldering tip.

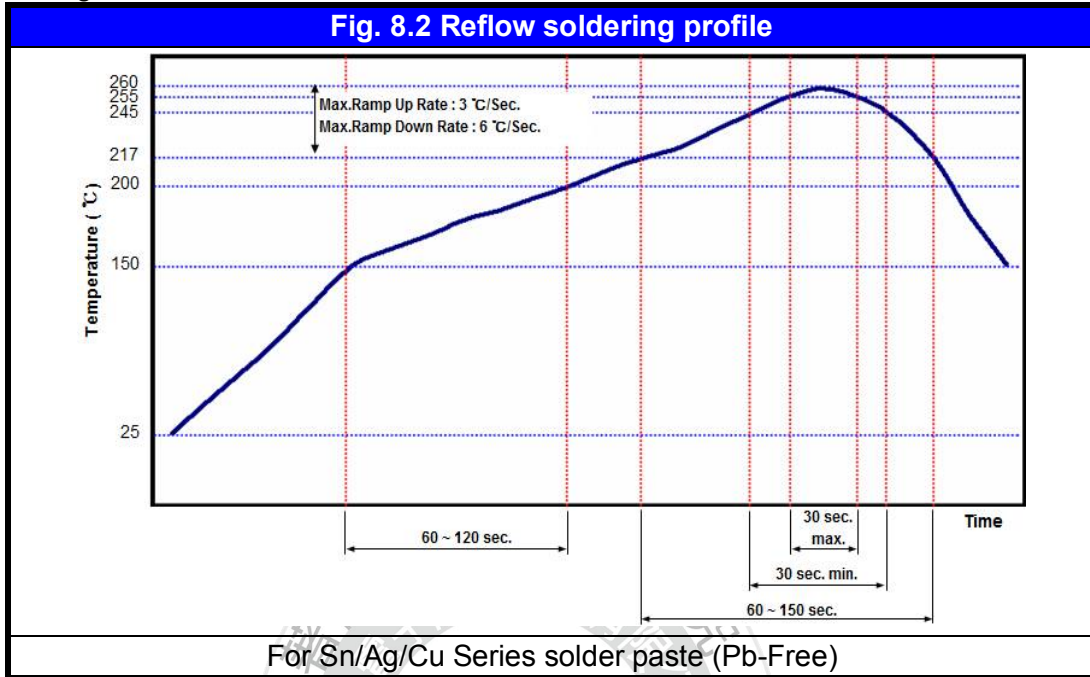
* The tip of iron should not contact the ceramic body directly.

* The Capacitors shall be cooled gradually at room temperature after soldering.

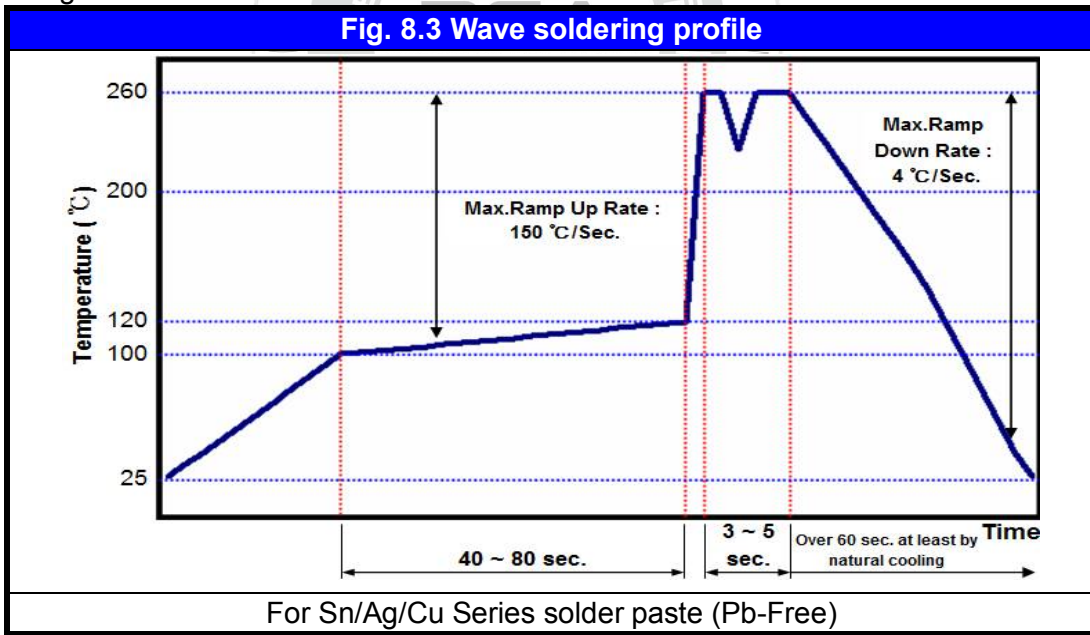
* Forced air cooling is not allowed.

8. APPLICATION NOTES

b.) Reflow soldering :



c.) Wave soldering :



Soldering conditions :

Class I :

Size Inch (mm)	Temper. Char.	Capacitance	Condition	
			Wave	Reflow
≤0402 (1005)	All Class I	All	X	O
0603 (1608)	All Class I	All	O	O
0805 (2012)	All Class I	All	O	O
1206 (3216)	All Class I	All	O	O
≥1210 (3225)	All Class I	All	X	O

8. APPLICATION NOTES

Soldering conditions :
 Class II :

Size Inch (mm)	Temper. Cher.	Capacitance	Condition	
			Wave	Reflow
≤0402 (1005)	All Class II	All	X	O
0603 (1608)	All Class II	Cap. <2.2μF	O	O
		Cap. ≥2.2μF	X	O
0805 (2012)	All Class II	Cap. <4.7μF	O	O
		Cap. ≥4.7μF	X	O
1206 (3216)	All Class II	Cap. <4.7μF	O	O
		Cap. ≥4.7μF	X	O
≥1210 (3225)	All Class II	All	X	O

Soldering height :

The solder climbing minimum height is suggesting to 25% of chip thickness or 500um whichever is less.
 (Reference from IPC-610E)

The diagram illustrates a cross-section of a chip on a substrate. The chip is shown in yellow and grey. A vertical double-headed arrow on the left indicates the 'Chip Thickness'. A horizontal double-headed arrow on the right indicates the 'Soldering Height', which is the height of the solder joint between the chip and the substrate.

COOLING

After soldering, cool the chips and the substrate gradually to room temperature. Natural cooling in air is recommended to minimize stress in the solder joint.

CLEANING

All flux residues must be removed by using suitable electronic-grade vapor-cleaning solvents to eliminate contamination that could cause electrolytic surface corrosion. Good results can be obtained by using ultrasonic cleaning of the solvent. The choice of the proper system is depends upon many factors such as component mix, flux, and solder paste and assembly method. The ability of the cleaning system to remove flux residues and contamination from under the chips is very important.